

*Coming Soon.....*  
0.4mm pitch SuperButton® Contactors

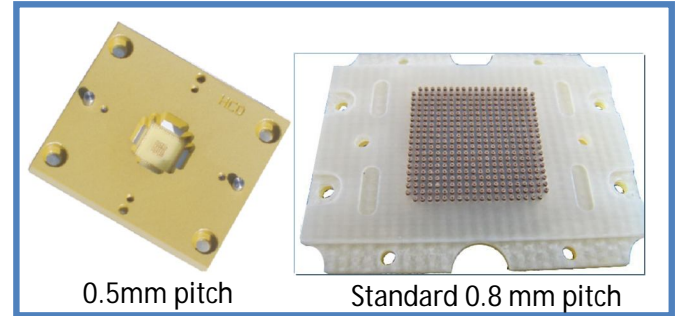
*The SuperButton® Advantage*

The proven performance of SuperButton® technology in a reduced size connector ideal for high density applications requiring pitches down to 0.4mm.

- SuperButton® connector technology is widely used in multiple applications across multiple market segments including Semiconductor, Medical Electronics, and Military & Aerospace.
- SuperButton® technology is continuously being used in high frequency, high current carrying capacity and high reliability designs since 1997
- SuperButton® connectors can be easily configured to any footprint providing enhanced flexibility at a competitive price
- HCD, Inc has worldwide sales and support infrastructure with dedicated applications and customer support team to provide design assistance for your applications
- All connector products from HCD are RoHS compliant and offers reduced carbon footprint

*Technology*

- HCD's SuperButton® is a proven solderless Z-axis connector technology that offers exceptional mechanical and electrical performance. At the heart of the technology is a continuous wire spring structure supported by elastomer
- Ideal for high performance applications for Board-to-Board, Flex-to-Board, Package-to-Board interconnect requirements
- Scalable interconnect technology that provides engineers a high performance, robust drop in replacement for pogo pins, fuzz buttons and other connector technologies



*Small Pitch Applications*

- Consumer electronics
- Medical Devices
- ATE
- Wafer Probe
- High density Board-to-Board modules

*SuperButton® Features & Benefits for Small Pitch Applications*

Features	Benefits
Signal Integrity	<ul style="list-style-type: none"> <li>• High Frequency (upto 26GHz BW)</li> <li>• Low Cres (&lt; 10mΩ)</li> <li>• High Current Rating (up to 7A/pin continuous)</li> <li>• Low Inductance (&lt; 0.9nH)</li> <li>• Low crosstalk</li> </ul>
High Density, Low Profile	<ul style="list-style-type: none"> <li>• Pitch as low as 0.4 mm</li> <li>• Low profile (as small as 0.8mm)</li> </ul>
Solderless Z-axis connection	<ul style="list-style-type: none"> <li>• Simple to use</li> <li>• Easy to rework</li> <li>• Field upgradeable</li> </ul>
Reliability	<ul style="list-style-type: none"> <li>• Up to 12 redundant contact points per button</li> <li>• Mechanical wipe under compression</li> <li>• Extremely stable connection over time and temperature</li> </ul>